



- NOTES:
- PLATING THICKNESS:
 ELBCTRO Ni : 1.27~8.89 MICRON. (SOLDER PADS)
 ELBCTRO Au : 0.70~1.20 MICRON. (SOLDER PADS)
 - CONNECTION:
 (1-VC). (2-INHN). (3-VSS-S/R). (4-Q). (5-VDD-D/A).
 (6-XT). (7-XTN). (NC-NC)
 - CAMBER : 50.00 MICRON MAX.
 - EXPOSURE OF CBAMIC SURFACE OCCURRED BY MISALIGNMENT OF THE UPPER LAYER. SHALL BE ALLOWED.
 - PART TO BE SHOWN AS SIDE METALLIZED PATTERN.
 - STRESS RELAXATION DESIGN SHALL BE APPLIED ON THIS ITEM.
 - SBALING METHOD OF THIS PRODUCT SHALL BE SBAM WBLD.

TOLERANCE	REVISION	SBB ATTACHED EXCEPTIONS SHEET.				TITLE
±% XX ±1% XXX N.L.T.±0.13 ANGLES	SCALE	DIMENSION	PROJECTION	CUSTOMER DWG NO.	REV.	5.0 X 7.0 VCXO PKG
	15 : 1	mm	3rd			PART NO. S5070VCXO1
MATERIAL	APPROVED	CHECKED	ENGRG	CHECKED	DESIGNED	REV. 0
90%MIN.A1203 INA-311B BLACK)	Shigetomi	Kawamura	Ohba	Kumura	Sugi	DWG NO. 1/7
	Sep.09.02	Sep.09.02	Sep.09.02	Sep.09.02	Sep.09.02	SHT/OF